



*From Nano to Micro Power Electronics
And Packaging Workshop
November 28th, 2024
Tours, France
15th Edition*



TECHNICAL PROGRAM

Technical Committee:

Daniel ALQUIER	TOURS University	France	Co-chairman
Laurent BARREAU	ST Microelectronics Tours	France	Chairman
Stéphane BELLENGER	ST Microelectronics Grenoble	France	Co-chairman
Lars BOETTCHER	FRAUNHOFER Institute	Germany	
Cyril BUTTAY	AMPERE Laboratory	France	
Jean-Luc DIOT	PRIVATE	France	
Franck DOSSEUL	MODULEUS	France	Co-chairman
Guo-Quan LU	VIRGINIA TECH	USA	

8 h 30 Workshop package and badge distribution

9 h 00 Welcome and workshop program presentation

9 h 15 Keynote: Cooling of power semiconductor devices : a challenge for high performance electrical power converters – Stéphane Azzopardi, Rabih Khazaka, Toni Youssef – Safran, France

10 h 05 Session 1: Designs, Applications & Reliability

10h 05 Impact of copper clip design on strains in power module packaging : a FEM analysis – Swan Abbès Moussa – CEA LETI, France

10 h 30 Coffee break / Table Top Exhibition and presentation

11 h 00 Session 1: Design, Applications & Reliability con't

11 h 00 Thermomechanical reliability of power modules bond wires undergoing power cycling – Mohamed Boutaleb – ST Microelectronics Tours, France

11 h 25 Overview of Si IPD technologies for power applications – Mohamed Jatlaoui – Murata, France

11 h 50 Method for early default detection in GaN-HEMT embedded PCB packaging – Alonso Gutierrez Galeano – CEA, France

12 h 15 Evaluation of breakdown in advanced molded substrates for power application package - Enrico Bottaro – ST Microelectronics Catania, Italy

12 h 40 Table Top Exhibition visit and Lunch (Buffet)

13 h 40 Session 2: Materials, Processes and Technologies

13 h 40 Next generation packaging materials for challenging AI and power electronics applications
– Anna Graf - Resonac, Germany

14 h 05 Electrification & automotive power electronics: innovative high reliability solder materials –
Karthik Vijay – Indium, United Kingdom

14 h 30 An exploration of silver sinter paste stencil printing parameters and the influence on print
quality – Valentin Divay – ST Microelectronics Munich, Germany

14 h 55 Material innovation for power module packaging – Lawrence Chong – Sumitomo,
Singapore

15 h 20 Coffee break / Table Top Exhibition

15 h 50 Session 2: Materials, Processes and Technologies con't

15 h 50 Characteristics of silver sintering with silver resin hybrid structure as an alternative for high
temperature lead solder – Shintaroh Abe - Tanaka, Japan

16 h 15 High precision capillary printing (HPCaP) for advanced interconnection and packaging
solutions – Achille Guitton – Hummink, France

16 h 40 Large area sintering for module attach – Thorsten Vehoff - Heraeus, Germany

17 h 05 Closing

17 h 15 End of session

List of exhibitors : ACCELONIX, DIGITCONCEPT, ELEMCA, HEF Group, KYOCERA,
MICRONOR, SERMA Microelectronics, CTS

Next to the workshop sessions of Thursday, November 28th, a social event will be organized to close the workshop day for which you need to register if you wish to attend:

- ***a visit of a wine cellar in Loire Valley. Departure from Greman's institute at 17h30***
- ***a dinner in a gastronomic restaurant in Tours at 20h00***



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Sponsors:

From Nano to Macro Power Electronics and Packaging European Workshop

Thursday, November 28th, 2024

GREMAN (ECOLE D'INGENIEURS POLYTECH TOURS)
Amphithéâtre du département électronique et énergie 7 avenue Marcel Dassault Tours

Registration Form
Final registration Thursday November 28^h 2024

COMPANY:

NAME:

FIRSTNAME:

ADDRESS:

TEL:

E-MAIL:

→Send back to IMAPS France by E-mail: imaps.france@orange.fr

FEES (including conferences attendance, table top visit, lunch, coffee breaks, social event and closing dinner)

Conferences on free access on website www.imapsfrance.org after the event.

- IMAPS MEMBER 210 € HT - 252 € TTC
- Non IMAPS MEMBER 260 € HT – 312 € TTC
- SPEAKERS/CHAIRS 160 € HT - 192 € TTC

For foreign companies, VAT is excluded

Do not forget to tick boxes if you want to participate to our social event

- Visit of a Touraine specific place (Thursday evening) yes no

- Dinner after the visit (Thursday evening) yes no

On line Payment and Registration available on www.france.imapseurope.org

PAYMENT BANK REFERENCES

Credit card accepted, as well as payment by cheque, cash or wire transfer.
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How to reach GREMAN



Access by car from the A10 motorway

In the Paris-Bordeaux direction,

Take the exit n ° 22 Saint-Avertin, then follow the direction of the 2 Lions.

In the Bordeaux-Paris direction,

Take the exit n ° 23, follow the direction Tours-Center then the 2 Lions direction

Access by train and tram or bus

You can either go to the Tours train station which is in the city center or to the Saint Pierre des Corps railway station which is on the outskirts and which has both rail shuttles to Tours and buses to different points of the city. More info on the website of Fil Bleu.

Access to Polytech Tours by tram stop "Fac 2 Lions" or by bus by line 5 stop "Polytech".